



ATTACHMENT A

Version With Markings to Show Changes Made

Please amend claims 1 and 5, as follows:

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1. (Twice Amended) A semiconductor device including a semiconductor chip having a principal surface and a back surface, opposite to said principal surface, disposed in a device hole provided in a tape carrier with one end of a lead on said tape carrier being electrically connected to an external terminal of said semiconductor chip, characterized in that said back surface of said semiconductor chip is defined by spin-etching a surface opposite to said semiconductor chip so that said semiconductor chip is less in thickness than said tape carrier, and that said semiconductor chip is sealed by a seal resin material [such that a] so that said principal surface and [a] said back surface of said semiconductor chip [is coated therewith] are covered with said seal resin material.

5. (Amended) The semiconductor device as recited in claim 1, characterized in that a [passage] seal resin injection port for use in seal resin injection is formed at part of said tape carrier thereby causing said device hole to be coupled to a gate of a metal mold structure used during formation of said seal resin.